



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * Cypress Semiconductor Corp	Company Unique ID CY	Unique ID Authority CY	Response Date * 2019-06-02	Response Document ID				
Contact Name * Quality Customer Support Gr	Title - Contact Quality Customer Support Group	Phone - Contact * 6328497500	Email - Contact * qacs_team@cypress.com	Duplicate Contact -> Authorized Representative				
Authorized Representative * Jeff Gary Ballesca	Title - Representative EH&S Engineer	Phone - Representative * 6328497500	Email - Representative * jgtb@cypress.com	Supplier Comments or URL for Additional Information				
Requester Item Number SP28	Mfr Item Number SSOP 28 (209 mil)	Mfr Item Name SSOP 28 (209 mil)	Effective Date 2019-06-02	Version CML	Manufacturing Site CML	Weight * 228.8	UOM mg	Unit Type Each
Alternate Recommendation				Alternate Item Comments	QTP No. 180909			

## Manufacturing Process Information

Terminal Plating / Grid Array Material Nickel/Palladium/Gold (Ni/Pd/Au)	Terminal Base Alloy CU Alloy	J-STD-020 MSL Rating 3	Peak Process Body Temperature 260 C	Max Time at Peak Temperature 30 seconds	Number of Reflow Cycles 3
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Comments

Test Reports: Mold Compound (001-79860) ; Die Attach (001-79586); Bonding Wire (001-82183); Leadframe (001-80096)

Save the fields in this form to a file

Export Data

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Import Data

Clear all of the fields on this form

Reset Form

Lock the fields on this form to prevent changes

Lock Supplier Fields

## RoHS Material Composition Declaration

Declaration Type \*

Detailed

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.

**RoHS Declaration \*** 1 - Item(s) does not contain RoHS restricted substances per the definition above

**Supplier Acceptance \*** Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem Name		Homogeneous Material	Weight	Unit of Measure		Level	Substance Category		Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM		
															-	+			
+I	-I	Leadframe	+M -M	Base Material	61.4138	mg	+C -C	Supplier	Cu	+S -S	Cu	7440-50-8		59.8476	mg			261,57	
									+C -C	Supplier	Fe	7439-89-6		1.4679	mg			6,416	
									+C -C	Supplier	P	7723-14-0		0.0369	mg			161	
									+C -C	Supplier	Zn	7440-66-6		0.0614	mg			268	
+I	-I	Lead Finish	+M -M	External Plating	0.6301	mg	+C -C	B	Nickel (external applic	+S -S	Nickel	7440-02-0		0.5041	mg			2,203	
									+C -C	Supplier	Pd	7440-05-3		0.011	mg			48	
									+C -C	Supplier	Au	7440-57-5		0.011	mg			48	
									+C -C	Supplier	Ag	7440-22-4		0.104	mg			454	
+I	-I	Die Attach	+M -M	Adhesive	1.178	mg	+C -C	Supplier	Ag	+S -S	Ag	7440-22-4		0.928	mg			4,056	
									+C -C	Supplier	Trade Secret Bismale	+S -S	Trade Secret Bismaleim	Trade Secre	0.091	mg			398
									+C -C	Supplier	Trade Secret Polyme	+S -S	Trade Secret Polymer	Trade Secre	0.063	mg			275
									+C -C	Supplier	Methacrylate	+S -S	Methacrylate	Trade Secre	0.032	mg			140
									+C -C	Supplier	Acrylate Ester	+S -S	Acrylate Ester	Trade Secre	0.032	mg			140
									+C -C	Supplier	Organic Peroxide	+S -S	Organic Peroxide	Trade Secre	0.032	mg			140
+I	-I	Die	+M -M	Circuit	15.88	mg	+C -C	Supplier	Si	+S -S	Si	7440-21-3		15.88	mg			69,406	
+I	-I	Wire	+M -M	Interconnect	1.956	mg	+C -C	Supplier	Au	+S -S	Au	7440-57-5		1.956	mg			8,549	
+I	-I	Mold Compound	+M -M	Encapsulation	147.742	mg	+C -C	Supplier	SiO2	+S -S	SiO2	Trade Secre		131.9214	mg			576,58	
									+C -C	Supplier	Phenol Resin	+S -S	Phenol Resin	Trade Secre	7.1645	mg			31,313
									+C -C	Supplier	Epoxy Resin	+S -S	Epoxy Resin	Trade Secre	8.6562	mg			37,833